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### Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	1879
Number of Logic Elements/Cells	24051
Total RAM Bits	958464
Number of I/O	190
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	324-LFBGA, CSPBGA
Supplier Device Package	324-CSPBGA (15x15)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/xilinx/xc6slx25t-2csg324i">https://www.e-xfl.com/product-detail/xilinx/xc6slx25t-2csg324i</a>

Table 2: Recommended Operating Conditions<sup>(1)</sup>

Symbol	Description		Min	Typ	Max	Units	
V <sub>CCINT</sub>	Internal supply voltage relative to GND	-3, -3N, -2	Standard performance <sup>(2)</sup>	1.14	1.2	1.26	V
		-3, -2	Extended performance <sup>(2)</sup>	1.2	1.23	1.26	V
		-1L	Standard performance <sup>(2)</sup>	0.95	1.0	1.05	V
V <sub>CCAUX</sub> <sup>(3)(4)</sup>	Auxiliary supply voltage relative to GND	V <sub>CCAUX</sub> = 2.5V <sup>(5)</sup>		2.375	2.5	2.625	V
		V <sub>CCAUX</sub> = 3.3V		3.15	3.3	3.45	V
V <sub>CCO</sub> <sup>(6)(7)(8)</sup>	Output supply voltage relative to GND		1.1	–	3.45	V	
V <sub>IN</sub>	Input voltage relative to GND	All I/O standards (except PCI)	Commercial temperature (C)	–0.5	–	4.0	V
			Industrial temperature (I)	–0.5	–	3.95	V
			Expanded (Q) temperature	–0.5	–	3.95	V
		PCI I/O standard <sup>(9)</sup>		–0.5	–	V <sub>CCO</sub> + 0.5	V
I <sub>IN</sub> <sup>(10)</sup>	Maximum current through pin using PCI I/O standard when forward biasing the clamp diode. <sup>(9)</sup>	Commercial (C) and Industrial temperature (I)		–	–	10	mA
		Expanded (Q) temperature		–	–	7	mA
V <sub>BATT</sub> <sup>(11)</sup>	Battery voltage relative to GND, T <sub>j</sub> = 0°C to +85°C (LX75, LX75T, LX100, LX100T, LX150, and LX150T only)		1.0	–	3.6	V	
T <sub>j</sub>	Junction temperature operating range	Commercial (C) range		0	–	85	°C
		Industrial temperature (I) range		–40	–	100	°C
		Expanded (Q) temperature range		–40	–	125	°C

**Notes:**

- All voltages are relative to ground.
- See *Interface Performances for Memory Interfaces* in Table 25. The extended performance range is specified for designs not using the standard V<sub>CCINT</sub> voltage range. The standard V<sub>CCINT</sub> voltage range is used for:
  - Designs that do not use an MCB
  - LX4 devices
  - Devices in the TQG144 or CPG196 packages
  - Devices with the -3N speed grade
- Recommended maximum voltage droop for V<sub>CCAUX</sub> is 10 mV/ms.
- During configuration, if V<sub>CCO\_2</sub> is 1.8V, then V<sub>CCAUX</sub> must be 2.5V.
- The -1L devices require V<sub>CCAUX</sub> = 2.5V when using the LVDS\_25, LVDS\_33, BLVDS\_25, LVPECL\_25, RSDS\_25, RSDS\_33, PPDS\_25, and PPDS\_33 I/O standards on inputs. LVPECL\_33 is not supported in the -1L devices.
- Configuration data is retained even if V<sub>CCO</sub> drops to 0V.
- Includes V<sub>CCO</sub> of 1.2V, 1.5V, 1.8V, 2.5V, and 3.3V.
- For PCI systems, the transmitter and receiver should have common supplies for V<sub>CCO</sub>.
- Devices with a -1L speed grade do not support Xilinx PCI IP.
- Do not exceed a total of 100 mA per bank.
- V<sub>BATT</sub> is required to maintain the battery backed RAM (BBR) AES key when V<sub>CCAUX</sub> is not applied. Once V<sub>CCAUX</sub> is applied, V<sub>BATT</sub> can be unconnected. When BBR is not used, Xilinx recommends connecting to V<sub>CCAUX</sub> or GND. However, V<sub>BATT</sub> can be unconnected.

## Quiescent Current

Typical values for quiescent supply current are specified at nominal voltage, 25°C junction temperatures ( $T_j$ ). Quiescent supply current is specified by speed grade for Spartan-6 devices. Xilinx recommends analyzing static power consumption using the XPOWER™ Estimator (XPE) tool (download at <http://www.xilinx.com/power>) for conditions other than those specified in Table 5.

Table 5: Typical Quiescent Supply Current

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
I <sub>CCINTQ</sub>	Quiescent V <sub>CCINT</sub> supply current	LX4	4.0	4.0	4.0	2.4	mA
		LX9	4.0	4.0	4.0	2.4	mA
		LX16	6.0	6.0	6.0	4.0	mA
		LX25	11.0	11.0	11.0	6.6	mA
		LX25T	11.0	11.0	11.0	N/A	mA
		LX45	15.0	15.0	15.0	9.0	mA
		LX45T	15.0	15.0	15.0	N/A	mA
		LX75	29.0	29.0	29.0	17.4	mA
		LX75T	29.0	29.0	29.0	N/A	mA
		LX100	36.0	36.0	36.0	21.6	mA
		LX100T	36.0	36.0	36.0	N/A	mA
		LX150	51.0	51.0	51.0	31.0	mA
		LX150T	51.0	51.0	51.0	N/A	mA
I <sub>CCOQ</sub>	Quiescent V <sub>CCO</sub> supply current	LX4	1.0	1.0	1.0	1.0	mA
		LX9	1.0	1.0	1.0	1.0	mA
		LX16	2.0	2.0	2.0	2.0	mA
		LX25	2.0	2.0	2.0	2.0	mA
		LX25T	2.0	2.0	2.0	N/A	mA
		LX45	3.0	3.0	3.0	3.0	mA
		LX45T	3.0	3.0	3.0	N/A	mA
		LX75	4.0	4.0	4.0	4.0	mA
		LX75T	4.0	4.0	4.0	N/A	mA
		LX100	5.0	5.0	5.0	5.0	mA
		LX100T	5.0	5.0	5.0	N/A	mA
		LX150	7.0	7.0	7.0	7.0	mA
		LX150T	7.0	7.0	7.0	N/A	mA

Table 14: GTP Transceiver Current Supply (per Lane)

Symbol	Description	Typ <sup>(1)</sup>	Max	Units
I <sub>MGTAVCC</sub>	GTP transceiver internal analog supply current	40.4	Note 2	mA
I <sub>MGTAVTTTX</sub>	GTP transmitter termination supply current	27.4		mA
I <sub>MGTAVTTRX</sub>	GTP receiver termination supply current	13.6		mA
I <sub>MGTAVCCPLL</sub>	GTP transmitter and receiver PLL supply current	28.7		mA
R <sub>MGTRREF</sub>	Precision reference resistor for internal calibration termination		50.0 ± 1% tolerance	Ω

**Notes:**

- Typical values are specified at nominal voltage, 25°C, with a 2.5 Gb/s line rate, with a shared PLL use mode.
- Values for currents of other transceiver configurations and conditions can be obtained by using the XPOWER Estimator (XPE) or XPOWER Analyzer (XPA) tools.

 Table 15: GTP Transceiver Quiescent Supply Current (per Lane)<sup>(1)(2)(3)(4)</sup>

Symbol	Description	Typ <sup>(5)</sup>	Max	Units
I <sub>MGTAVCCQ</sub>	Quiescent MGTAVCC supply current	1.7	Note 2	mA
I <sub>MGTAVTTTXQ</sub>	Quiescent MGTAVTTTX supply current	0.1		mA
I <sub>MGTAVTTRXQ</sub>	Quiescent MGTAVTTRX supply current	1.2		mA
I <sub>MGTAVCCPLLQ</sub>	Quiescent MGTAVCCPLL supply current	1.0		mA

**Notes:**

- Device powered and unconfigured.
- Currents for conditions other than values specified in this table can be obtained by using the XPOWER Estimator (XPE) or XPOWER Analyzer (XPA) tools.
- GTP transceiver quiescent supply current for an entire device can be calculated by multiplying the values in this table by the number of available GTP transceivers.
- Does not include power-up MGTAVTTRCAL supply current during device configuration.
- Typical values are specified at nominal voltage, 25°C.

## GTP Transceiver DC Input and Output Levels

Table 16 summarizes the DC output specifications of the GTP transceivers in Spartan-6 FPGAs. Figure 1 shows the single-ended output voltage swing. Figure 2 shows the peak-to-peak differential output voltage.

Consult UG386: *Spartan-6 FPGA GTP Transceivers User Guide* for further details.

Table 16: GTP Transceiver DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
DV <sub>PPIN</sub>	Differential peak-to-peak input voltage	External AC coupled	140	–	2000	mV
V <sub>IN</sub>	Absolute input voltage	DC coupled MGTAVTTRX = 1.2V	–400	–	MGTAVTTRX	mV
V <sub>CMIN</sub>	Common mode input voltage	DC coupled MGTAVTTRX = 1.2V	–	3/4 MGTAVTTRX	–	mV
DV <sub>PPOUT</sub>	Differential peak-to-peak output voltage <sup>(1)</sup>	Transmitter output swing is set to maximum setting	–	–	1000	mV
V <sub>SEOUT</sub>	Single-ended output voltage swing <sup>(1)</sup>		–	–	500	mV
V <sub>CMOUTDC</sub>	Common mode output voltage	Equation based	MGTAVTTTX – V <sub>SEOUT</sub> /2			mV
R <sub>IN</sub>	Differential input resistance		80	100	130	Ω
R <sub>OUT</sub>	Differential output resistance		80	100	130	Ω
T <sub>OSKEW</sub>	Transmitter output skew		–	–	15	ps
C <sub>EXT</sub>	Recommended external AC coupling capacitor <sup>(2)</sup>		75	100	200	nF

**Notes:**

1. The output swing and preemphasis levels are programmable using the attributes discussed in UG386: *Spartan-6 FPGA GTP Transceivers User Guide* and can result in values lower than reported in this table.
2. Other values can be used as appropriate to conform to specific protocols and standards.

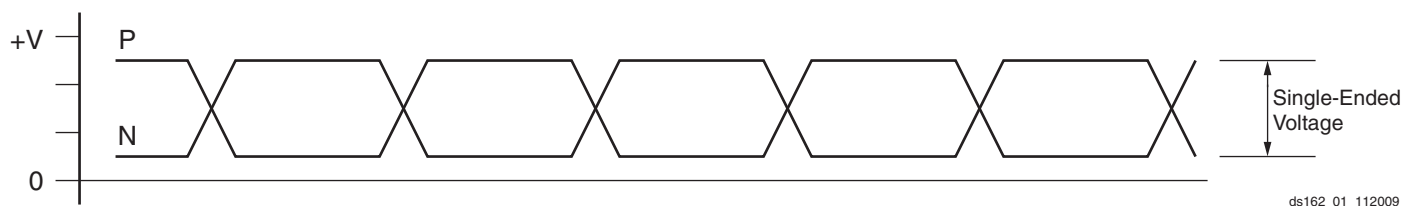


Figure 1: Single-Ended Peak-to-Peak Voltage

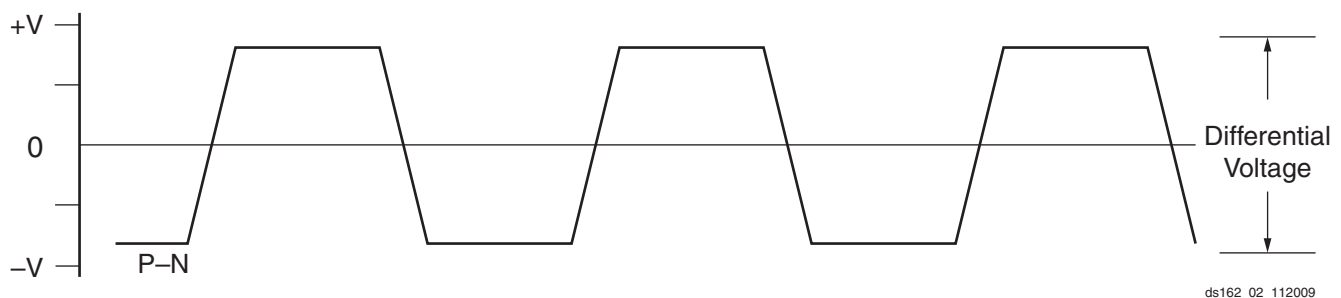


Figure 2: Differential Peak-to-Peak Voltage

Table 17 summarizes the DC specifications of the clock input of the GTP transceiver. Consult UG386: *Spartan-6 FPGA GTP Transceivers User Guide* for further details.

Table 23: GTP Transceiver Receiver Switching Characteristics

Symbol	Description		Min	Typ	Max	Units	
T <sub>RXELECIDLE</sub>	Time for RXELECIDLE to respond to loss or restoration of data		–	75	–	ns	
R <sub>XOOBVDPP</sub>	OOB detect threshold peak-to-peak		60	–	150	mV	
R <sub>XSSST</sub>	Receiver spread-spectrum tracking <sup>(1)</sup>	Modulated @ 33 KHz	–5000	–	0	ppm	
R <sub>XRL</sub>	Run length (CID)	Internal AC capacitor bypassed	–	–	150	UI	
R <sub>XPPMTOL</sub>	Data/REFCLK PPM offset tolerance	CDR 2 <sup>nd</sup> -order loop disabled	–200	–	200	ppm	
		CDR 2 <sup>nd</sup> -order loop enabled	PLL_RXDIVSEL_OUT = 1	–2000	–	2000	ppm
			PLL_RXDIVSEL_OUT = 2	–2000	–	2000	ppm
		PLL_RXDIVSEL_OUT = 4	–1000	–	1000	ppm	
<b>SJ Jitter Tolerance<sup>(2)</sup></b>							
JT_SJ <sub>3.125</sub>	Sinusoidal Jitter <sup>(3)</sup>	3.125 Gb/s	0.4	–	–	UI	
JT_SJ <sub>2.5</sub>	Sinusoidal Jitter <sup>(3)</sup>	2.5 Gb/s	0.4	–	–	UI	
JT_SJ <sub>1.62</sub>	Sinusoidal Jitter <sup>(3)</sup>	1.62 Gb/s	0.5	–	–	UI	
JT_SJ <sub>1.25</sub>	Sinusoidal Jitter <sup>(3)</sup>	1.25 Gb/s	0.5	–	–	UI	
JT_SJ <sub>614</sub>	Sinusoidal Jitter <sup>(3)</sup>	614 Mb/s	0.5	–	–	UI	
<b>SJ Jitter Tolerance with Stressed Eye<sup>(2)(5)</sup></b>							
JT_TJSE <sub>3.125</sub>	Total Jitter with stressed eye <sup>(4)</sup>	3.125 Gb/s	0.65	–	–	UI	
JT_SJSE <sub>3.125</sub>	Sinusoidal Jitter with stressed eye	3.125 Gb/s	0.1	–	–	UI	
JT_TJSE <sub>2.7</sub>	Total Jitter with stressed eye <sup>(4)</sup>	2.7 Gb/s	0.65	–	–	UI	
JT_SJSE <sub>2.7</sub>	Sinusoidal Jitter with stressed eye	2.7 Gb/s	0.1	–	–	UI	

**Notes:**

- Using PLL\_RXDIVSEL\_OUT = 1, 2, and 4.
- All jitter values are based on a Bit Error Ratio of 1e<sup>-12</sup>.
- Using 80 MHz sinusoidal jitter only in the absence of deterministic and random jitter.
- Composed of 0.37 UI DJ in the form of ISI and 0.18 UI RJ.
- Measured using PRBS7 data pattern.

## Endpoint Block for PCI Express Designs Switching Characteristics

The Endpoint block for PCI Express is available in the Spartan-6 LXT devices. Consult the [Spartan-6 FPGA Integrated Endpoint Block for PCI Express](#) for further information.

Table 24: Maximum Performance for PCI Express Designs

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
F <sub>PCIEUSER</sub>	User clock maximum frequency	62.5	62.5	62.5	N/A	MHz

Table 28: IOB Switching Characteristics for the Commercial (XC) Spartan-6 Devices (Cont'd)

I/O Standard	T <sub>IOPI</sub>				T <sub>IOOP</sub>				T <sub>IOTP</sub>				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	
PPDS_33	1.17	1.29	1.42	1.68	1.57	1.71	1.91	2.43	3000	3000	3000	3000	ns
PPDS_25	1.01	1.13	1.26	1.56	1.68	1.82	2.02	2.47	3000	3000	3000	3000	ns
PCI33_3	1.07	1.19	1.32	1.57 <sup>(2)</sup>	3.51	3.65	3.85	4.38 <sup>(2)</sup>	3.51	3.65	3.85	4.38 <sup>(1)</sup>	ns
PCI66_3	1.07	1.19	1.32	1.57 <sup>(2)</sup>	3.53	3.67	3.87	4.39 <sup>(2)</sup>	3.53	3.67	3.87	4.39 <sup>(1)</sup>	ns
DISPLAY_PORT	1.02	1.14	1.27	1.56	3.15	3.29	3.49	4.08	3.15	3.29	3.49	4.08	ns
I2C	1.33	1.45	1.58	1.82	11.56	11.70	11.90	12.52	11.56	11.70	11.90	12.52	ns
SMBUS	1.33	1.45	1.58	1.82	11.56	11.70	11.90	12.52	11.56	11.70	11.90	12.52	ns
SDIO	1.36	1.48	1.61	1.84	2.64	2.78	2.98	3.60	2.64	2.78	2.98	3.60	ns
MOBILE_DDR	0.94	1.06	1.19	1.43	2.35	2.49	2.69	3.31	2.35	2.49	2.69	3.31	ns
HSTL_I	0.90	1.02	1.15	1.39	1.66	1.80	2.00	2.62	1.66	1.80	2.00	2.62	ns
HSTL_II	0.91	1.03	1.16	1.40	1.72	1.86	2.06	2.68	1.72	1.86	2.06	2.68	ns
HSTL_III	0.95	1.07	1.20	1.44	1.67	1.81	2.01	2.61	1.67	1.81	2.01	2.61	ns
HSTL_I_18	0.94	1.06	1.19	1.43	1.77	1.91	2.11	2.73	1.77	1.91	2.11	2.73	ns
HSTL_II_18	0.94	1.06	1.19	1.43	1.85	1.99	2.19	2.81	1.85	1.99	2.19	2.81	ns
HSTL_III_18	0.99	1.11	1.24	1.47	1.79	1.93	2.13	2.72	1.79	1.93	2.13	2.72	ns
SSTL3_I	1.58	1.70	1.83	2.16	1.83	1.97	2.17	2.72	1.83	1.97	2.17	2.72	ns
SSTL3_II	1.58	1.70	1.83	2.16	2.01	2.15	2.35	2.94	2.01	2.15	2.35	2.94	ns
SSTL2_I	1.30	1.42	1.55	1.87	1.77	1.91	2.11	2.69	1.77	1.91	2.11	2.69	ns
SSTL2_II	1.30	1.42	1.55	1.88	1.86	2.00	2.20	2.82	1.86	2.00	2.20	2.82	ns
SSTL18_I	0.92	1.04	1.17	1.41	1.63	1.77	1.97	2.59	1.63	1.77	1.97	2.59	ns
SSTL18_II	0.92	1.04	1.17	1.41	1.66	1.80	2.00	2.62	1.66	1.80	2.00	2.62	ns
SSTL15_II	0.92	1.04	1.17	1.41	1.67	1.81	2.01	2.63	1.67	1.81	2.01	2.63	ns
DIFF_HSTL_I	0.94	1.06	1.19	1.46	1.77	1.91	2.11	2.62	1.77	1.91	2.11	2.62	ns
DIFF_HSTL_II	0.93	1.05	1.18	1.45	1.72	1.86	2.06	2.54	1.72	1.86	2.06	2.54	ns
DIFF_HSTL_III	0.93	1.05	1.18	1.46	1.69	1.83	2.03	2.53	1.69	1.83	2.03	2.53	ns
DIFF_HSTL_I_18	0.97	1.09	1.22	1.50	1.79	1.93	2.13	2.63	1.79	1.93	2.13	2.63	ns
DIFF_HSTL_II_18	0.97	1.09	1.22	1.49	1.69	1.83	2.03	2.51	1.69	1.83	2.03	2.51	ns
DIFF_HSTL_III_18	0.97	1.09	1.22	1.50	1.69	1.83	2.03	2.53	1.69	1.83	2.03	2.53	ns
DIFF_SSTL3_I	1.18	1.30	1.43	1.68	1.81	1.95	2.15	2.64	1.81	1.95	2.15	2.64	ns
DIFF_SSTL3_II	1.19	1.31	1.44	1.68	1.80	1.94	2.14	2.63	1.80	1.94	2.14	2.63	ns
DIFF_SSTL2_I	1.02	1.14	1.27	1.57	1.80	1.94	2.14	2.62	1.80	1.94	2.14	2.62	ns
DIFF_SSTL2_II	1.02	1.14	1.27	1.57	1.76	1.90	2.10	2.57	1.76	1.90	2.10	2.57	ns
DIFF_SSTL18_I	0.97	1.09	1.22	1.51	1.72	1.86	2.06	2.56	1.72	1.86	2.06	2.56	ns
DIFF_SSTL18_II	0.98	1.10	1.23	1.50	1.68	1.82	2.02	2.52	1.68	1.82	2.02	2.52	ns
DIFF_SSTL15_II	0.94	1.06	1.19	1.46	1.67	1.81	2.01	2.50	1.67	1.81	2.01	2.50	ns
DIFF_MOBILE_DDR	0.97	1.09	1.22	1.51	1.75	1.89	2.09	2.57	1.75	1.89	2.09	2.57	ns

Table 28: IOB Switching Characteristics for the Commercial (XC) Spartan-6 Devices (Cont'd)

I/O Standard	T <sub>IOPI</sub>				T <sub>IOOP</sub>				T <sub>IOTP</sub>				Units
	Speed Grade				Speed Grade				Speed Grade				
	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	-3	-3N	-2	-1L <sup>(1)</sup>	
LVC MOS33, Fast, 8 mA	1.34	1.46	1.59	1.82	2.07	2.21	2.41	3.03	2.07	2.21	2.41	3.03	ns
LVC MOS33, Fast, 12 mA	1.34	1.46	1.59	1.82	1.65	1.79	1.99	2.62	1.65	1.79	1.99	2.62	ns
LVC MOS33, Fast, 16 mA	1.34	1.46	1.59	1.82	1.65	1.79	1.99	2.62	1.65	1.79	1.99	2.62	ns
LVC MOS33, Fast, 24 mA	1.34	1.46	1.59	1.82	1.65	1.79	1.99	2.62	1.65	1.79	1.99	2.62	ns
LVC MOS25, QUIETIO, 2 mA	0.82	0.94	1.07	1.31	4.81	4.95	5.15	5.79	4.81	4.95	5.15	5.79	ns
LVC MOS25, QUIETIO, 4 mA	0.82	0.94	1.07	1.31	3.70	3.84	4.04	4.66	3.70	3.84	4.04	4.66	ns
LVC MOS25, QUIETIO, 6 mA	0.82	0.94	1.07	1.31	3.46	3.60	3.80	4.38	3.46	3.60	3.80	4.38	ns
LVC MOS25, QUIETIO, 8 mA	0.82	0.94	1.07	1.31	3.20	3.34	3.54	4.12	3.20	3.34	3.54	4.12	ns
LVC MOS25, QUIETIO, 12 mA	0.82	0.94	1.07	1.31	2.83	2.97	3.17	3.75	2.83	2.97	3.17	3.75	ns
LVC MOS25, QUIETIO, 16 mA	0.82	0.94	1.07	1.31	2.64	2.78	2.98	3.64	2.64	2.78	2.98	3.64	ns
LVC MOS25, QUIETIO, 24 mA	0.82	0.94	1.07	1.31	2.45	2.59	2.79	3.42	2.45	2.59	2.79	3.42	ns
LVC MOS25, Slow, 2 mA	0.82	0.94	1.07	1.31	3.78	3.92	4.12	4.76	3.78	3.92	4.12	4.76	ns
LVC MOS25, Slow, 4 mA	0.82	0.94	1.07	1.31	2.79	2.93	3.13	3.73	2.79	2.93	3.13	3.73	ns
LVC MOS25, Slow, 6 mA	0.82	0.94	1.07	1.31	2.73	2.87	3.07	3.66	2.73	2.87	3.07	3.66	ns
LVC MOS25, Slow, 8 mA	0.82	0.94	1.07	1.31	2.48	2.62	2.82	3.42	2.48	2.62	2.82	3.42	ns
LVC MOS25, Slow, 12 mA	0.82	0.94	1.07	1.31	2.01	2.15	2.35	2.95	2.01	2.15	2.35	2.95	ns
LVC MOS25, Slow, 16 mA	0.82	0.94	1.07	1.31	2.01	2.15	2.35	2.95	2.01	2.15	2.35	2.95	ns
LVC MOS25, Slow, 24 mA	0.82	0.94	1.07	1.31	2.01	2.15	2.35	2.94	2.01	2.15	2.35	2.94	ns
LVC MOS25, Fast, 2 mA	0.82	0.94	1.07	1.31	3.35	3.49	3.69	4.31	3.35	3.49	3.69	4.31	ns
LVC MOS25, Fast, 4 mA	0.82	0.94	1.07	1.31	2.25	2.39	2.59	3.22	2.25	2.39	2.59	3.22	ns
LVC MOS25, Fast, 6 mA	0.82	0.94	1.07	1.31	2.09	2.23	2.43	3.05	2.09	2.23	2.43	3.05	ns
LVC MOS25, Fast, 8 mA	0.82	0.94	1.07	1.31	2.02	2.16	2.36	2.98	2.02	2.16	2.36	2.98	ns
LVC MOS25, Fast, 12 mA	0.82	0.94	1.07	1.31	1.56	1.70	1.90	2.52	1.56	1.70	1.90	2.52	ns
LVC MOS25, Fast, 16 mA	0.82	0.94	1.07	1.31	1.56	1.70	1.90	2.52	1.56	1.70	1.90	2.52	ns
LVC MOS25, Fast, 24 mA	0.82	0.94	1.07	1.31	1.56	1.70	1.90	2.52	1.56	1.70	1.90	2.52	ns
LVC MOS18, QUIETIO, 2 mA	1.18	1.30	1.43	2.04	5.92	6.06	6.26	6.80	5.92	6.06	6.26	6.80	ns
LVC MOS18, QUIETIO, 4 mA	1.18	1.30	1.43	2.04	4.74	4.88	5.08	5.63	4.74	4.88	5.08	5.63	ns
LVC MOS18, QUIETIO, 6 mA	1.18	1.30	1.43	2.04	4.05	4.19	4.39	4.96	4.05	4.19	4.39	4.96	ns
LVC MOS18, QUIETIO, 8 mA	1.18	1.30	1.43	2.04	3.71	3.85	4.05	4.63	3.71	3.85	4.05	4.63	ns
LVC MOS18, QUIETIO, 12 mA	1.18	1.30	1.43	2.04	3.35	3.49	3.69	4.27	3.35	3.49	3.69	4.27	ns
LVC MOS18, QUIETIO, 16 mA	1.18	1.30	1.43	2.04	3.20	3.34	3.54	4.14	3.20	3.34	3.54	4.14	ns
LVC MOS18, QUIETIO, 24 mA	1.18	1.30	1.43	2.04	2.96	3.10	3.30	3.98	2.96	3.10	3.30	3.98	ns
LVC MOS18, Slow, 2 mA	1.18	1.30	1.43	2.04	4.62	4.76	4.96	5.54	4.62	4.76	4.96	5.54	ns
LVC MOS18, Slow, 4 mA	1.18	1.30	1.43	2.04	3.69	3.83	4.03	4.60	3.69	3.83	4.03	4.60	ns
LVC MOS18, Slow, 6 mA	1.18	1.30	1.43	2.04	3.00	3.14	3.34	3.94	3.00	3.14	3.34	3.94	ns
LVC MOS18, Slow, 8 mA	1.18	1.30	1.43	2.04	2.19	2.33	2.53	3.17	2.19	2.33	2.53	3.17	ns
LVC MOS18, Slow, 12 mA	1.18	1.30	1.43	2.04	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns
LVC MOS18, Slow, 16 mA	1.18	1.30	1.43	2.04	1.99	2.13	2.33	2.95	1.99	2.13	2.33	2.95	ns



Table 29: IOB Switching Characteristics for the Automotive XA Spartan-6 and the Spartan-6Q Devices<sup>(1)</sup> (Cont'd)

I/O Standard	T <sub>IOPI</sub>		T <sub>IOOP</sub>		T <sub>IOTP</sub>		Units
	Speed Grade		Speed Grade		Speed Grade		
	-3	-2	-3	-2	-3	-2	
LVC MOS12, QUIETIO, 6 mA	0.98	1.16	4.79	4.99	4.79	4.99	ns
LVC MOS12, QUIETIO, 8 mA	0.98	1.16	4.43	4.63	4.43	4.63	ns
LVC MOS12, QUIETIO, 12 mA	0.98	1.16	4.18	4.38	4.18	4.38	ns
LVC MOS12, Slow, 2 mA	0.98	1.16	5.12	5.32	5.12	5.32	ns
LVC MOS12, Slow, 4 mA	0.98	1.16	3.00	3.20	3.00	3.20	ns
LVC MOS12, Slow, 6 mA	0.98	1.16	2.91	3.11	2.91	3.11	ns
LVC MOS12, Slow, 8 mA	0.98	1.16	2.51	2.71	2.51	2.71	ns
LVC MOS12, Slow, 12 mA	0.98	1.16	2.25	2.45	2.25	2.45	ns
LVC MOS12, Fast, 2 mA	0.98	1.16	3.60	3.80	3.60	3.80	ns
LVC MOS12, Fast, 4 mA	0.98	1.16	2.49	2.69	2.49	2.69	ns
LVC MOS12, Fast, 6 mA	0.98	1.16	1.94	2.14	1.94	2.14	ns
LVC MOS12, Fast, 8 mA	0.98	1.16	1.82	2.02	1.82	2.02	ns
LVC MOS12, Fast, 12 mA	0.98	1.16	1.80	2.00	1.80	2.00	ns
LVC MOS12_JEDEC, QUIETIO, 2 mA	1.57	1.75	6.53	6.73	6.53	6.73	ns
LVC MOS12_JEDEC, QUIETIO, 4 mA	1.57	1.75	5.12	5.32	5.12	5.32	ns
LVC MOS12_JEDEC, QUIETIO, 6 mA	1.57	1.75	4.81	5.01	4.81	5.01	ns
LVC MOS12_JEDEC, QUIETIO, 8 mA	1.57	1.75	4.44	4.64	4.44	4.64	ns
LVC MOS12_JEDEC, QUIETIO, 12 mA	1.57	1.75	4.20	4.40	4.20	4.40	ns
LVC MOS12_JEDEC, Slow, 2 mA	1.57	1.75	5.14	5.34	5.14	5.34	ns
LVC MOS12_JEDEC, Slow, 4 mA	1.57	1.75	2.99	3.19	2.99	3.19	ns
LVC MOS12_JEDEC, Slow, 6 mA	1.57	1.75	2.90	3.10	2.90	3.10	ns
LVC MOS12_JEDEC, Slow, 8 mA	1.57	1.75	2.50	2.70	2.50	2.70	ns
LVC MOS12_JEDEC, Slow, 12 mA	1.57	1.75	2.26	2.46	2.26	2.46	ns
LVC MOS12_JEDEC, Fast, 2 mA	1.57	1.75	3.60	3.80	3.60	3.80	ns
LVC MOS12_JEDEC, Fast, 4 mA	1.57	1.75	2.49	2.69	2.49	2.69	ns
LVC MOS12_JEDEC, Fast, 6 mA	1.57	1.75	1.94	2.14	1.94	2.14	ns
LVC MOS12_JEDEC, Fast, 8 mA	1.57	1.75	1.83	2.03	1.83	2.03	ns
LVC MOS12_JEDEC, Fast, 12 mA	1.57	1.75	1.80	2.00	1.80	2.00	ns

Notes:

1. The Spartan-6Q FPGA -1L values are listed in Table 28.

Table 30 summarizes the value of T<sub>IOTPHZ</sub>. T<sub>IOTPHZ</sub> is described as the delay from the T pin to the IOB pad through the output buffer of an IOB pad, when 3-state is enabled (i.e., a high impedance state). These delays are measured using LVC MOS25, Fast, 12 mA.

Table 30: IOB 3-state ON Output Switching Characteristics (T<sub>IOTPHZ</sub>)

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
T <sub>IOTPHZ</sub>	T input to Pad high-impedance	1.39	1.59	1.59	1.91	ns

### Output Delay Measurements

Output delays are measured using a Tektronix P6245 TDS500/600 probe (< 1 pF) across approximately 4" of FR4 microstrip trace. Standard termination was used for all testing. The propagation delay of the 4" trace is characterized separately and subtracted from the final measurement, and is therefore not included in the generalized test setups shown in Figure 4 and Figure 5.

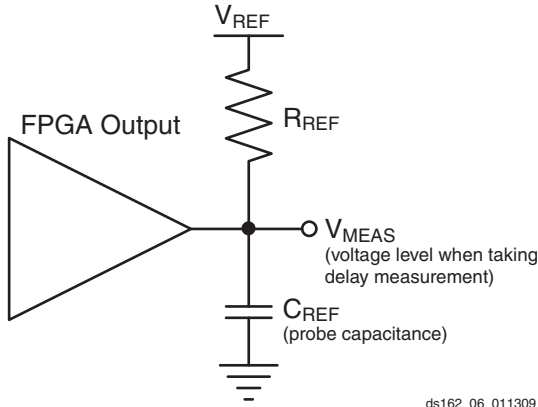
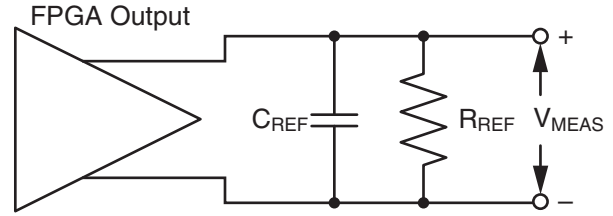


Figure 4: Single-Ended Test Setup



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Figure 5: Differential Test Setup

Measurements and test conditions are reflected in the IBIS models except where the IBIS format precludes it. Parameters  $V_{REF}$ ,  $R_{REF}$ ,  $C_{REF}$ , and  $V_{MEAS}$  fully describe the test conditions for each I/O standard. The most accurate prediction of propagation delay in any given application can be obtained through IBIS simulation, using the following method:

1. Simulate the output driver of choice into the generalized test setup, using values from Table 32.
2. Record the time to  $V_{MEAS}$ .
3. Simulate the output driver of choice into the actual PCB trace and load, using the appropriate IBIS model or capacitance value to represent the load.
4. Record the time to  $V_{MEAS}$ .
5. Compare the results of steps 2 and 4. The increase or decrease in delay yields the actual propagation delay of the PCB trace.

Table 32: Output Delay Measurement Methodology

Description	I/O Standard Attribute	$R_{REF}$ ( $\Omega$ )	$C_{REF}^{(1)}$ (pF)	$V_{MEAS}$ (V)	$V_{REF}$ (V)
LVTTTL (Low-Voltage Transistor-Transistor Logic)	LVTTTL (all)	1M	0	1.4	0
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	1M	0	1.65	0
LVC MOS, 2.5V	LVC MOS25	1M	0	1.25	0
LVC MOS, 1.8V	LVC MOS18	1M	0	0.9	0
LVC MOS, 1.5V	LVC MOS15	1M	0	0.75	0
LVC MOS, 1.2V	LVC MOS12	1M	0	0.6	0
PCI (Peripheral Component Interface) 33 MHz and 66 MHz, 3.3V	PCI33_3, PCI66_3 (rising edge)	25	10 <sup>(2)</sup>	0.94	0
	PCI33_3, PCI66_3 (falling edge)	25	10 <sup>(2)</sup>	2.03	3.3
HSTL (High-Speed Transceiver Logic), Class I	HSTL_I	50	0	$V_{REF}$	0.75
HSTL, Class II	HSTL_II	25	0	$V_{REF}$	0.75
HSTL, Class III	HSTL_III	50	0	0.9	1.5
HSTL, Class I, 1.8V	HSTL_I_18	50	0	$V_{REF}$	0.9
HSTL, Class II, 1.8V	HSTL_II_18	25	0	$V_{REF}$	0.9
HSTL, Class III, 1.8V	HSTL_III_18	50	0	1.1	1.8
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	50	0	$V_{REF}$	0.9
SSTL, Class II, 1.8V	SSTL18_II	25	0	$V_{REF}$	0.9
SSTL, Class I, 2.5V	SSTL2_I	50	0	$V_{REF}$	1.25

Table 34: SSO Limit per V<sub>CCO</sub>/GND Pair (Cont'd)

V <sub>CCO</sub>	I/O Standard	Drive	Slew	SSO Limit per V <sub>CCO</sub> /GND Pair			
				All TQG144, CPG196, CSG225, FT(G)256, and LX devices in CSG324		All CS(G)484, FG(G)484, FG(G)676, FG(G)900, and LXT devices in CSG324	
				Bank 0/2	Bank 1/3	Bank 0/2	Bank 1/3/4/5
3.3V	LVCMOS33	2	Fast	42	46	42	44
			Slow	50	55	50	49
			QuietIO	60	68	60	60
		4	Fast	21	27	21	25
			Slow	32	37	32	32
			QuietIO	39	42	39	37
		6	Fast	14	19	14	17
			Slow	19	25	19	22
			QuietIO	29	30	29	25
		8	Fast	11	15	11	14
			Slow	15	20	15	18
			QuietIO	25	24	25	20
		12	Fast	1	3	1	1
			Slow	2	5	2	2
			QuietIO	4	9	4	7
		16	Fast	1	2	1	1
			Slow	1	5	1	1
			QuietIO	3	10	3	8
		24	Fast	1	2	1	1
			Slow	2	5	2	1
			QuietIO	7	9	7	7

## Input/Output Delay Switching Characteristics

Table 39: IODELAY2 Switching Characteristics

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L <sup>(3)</sup>	
$T_{\text{IODCCK\_CAL}} / T_{\text{IODCKC\_CAL}}$	CAL pin Setup/Hold with respect to CK	0.28/ -0.13	0.33/ -0.13	0.48/ -0.13	N/A	ns
$T_{\text{IODCCK\_CE}} / T_{\text{IODCKC\_CE}}$	CE pin Setup/Hold with respect to CK	0.17/ -0.03	0.17/ -0.03	0.25/ -0.02	N/A	ns
$T_{\text{IODCCK\_INC}} / T_{\text{IODCKC\_INC}}$	INC pin Setup/Hold with respect to CK	0.10/ 0.02	0.12/ 0.03	0.18/ 0.06	N/A	ns
$T_{\text{IODCCK\_RST}} / T_{\text{IODCKC\_RST}}$	RST pin Setup/Hold with respect to CK	0.12/ -0.02	0.15/ -0.02	0.22/ -0.01	N/A	ns
$T_{\text{TAP1}}^{(2)}$	Maximum tap 1 delay	8	14	16	N/A	ps
$T_{\text{TAP2}}$	Maximum tap 2 delay	40	66	77	N/A	ps
$T_{\text{TAP3}}$	Maximum tap 3 delay	95	120	140	N/A	ps
$T_{\text{TAP4}}$	Maximum tap 4 delay	108	141	166	N/A	ps
$T_{\text{TAP5}}$	Maximum tap 5 delay	171	194	231	N/A	ps
$T_{\text{TAP6}}$	Maximum tap 6 delay	207	249	292	N/A	ps
$T_{\text{TAP7}}$	Maximum tap 7 delay	212	276	343	N/A	ps
$T_{\text{TAP8}}$	Maximum tap 8 delay	322	341	424	N/A	ps
$F_{\text{MINCAL}}$	Minimum allowed bit rate for calibration in variable mode: VARIABLE_FROM_ZERO, VARIABLE_FROM_HALF_MAX, and DIFF_PHASE_DETECTOR.	188	188	188	N/A	Mb/s
$T_{\text{IODDO\_IDATAIN}}$	Propagation delay through IODELAY2	Note 1	Note 1	Note 1	Note 3	–
$T_{\text{IODDO\_ODATAIN}}$	Propagation delay through IODELAY2	Note 1	Note 1	Note 1	Note 3	–

### Notes:

- Delay depends on IODELAY2 tap setting. See TRACE report for actual values.
- Maximum delay = integer (number of taps/8)  $\times$   $T_{\text{TAP8}}$  +  $T_{\text{TAPn}}$  (where n equals the remainder). For minimum delay consult the TRACE setup and hold report. Minimum delay is typically greater than 30% of the maximum delay. Tap delays can vary by device and overall conditions. See TRACE report for actual values.
- Spartan-6 -1L devices only support tap 0. See TRACE report for actual values.

Table 45: Device DNA Interface Port Switching Characteristics

Symbol	Description	Speed Grade				Units
		-3	-3N	-2	-1L	
T <sub>DNASSU</sub>	Setup time on SHIFT before the rising edge of CLK	7				ns, Min
T <sub>DNASH</sub>	Hold time on SHIFT after the rising edge of CLK	1				ns, Min
T <sub>DNADSU</sub>	Setup time on DIN before the rising edge of CLK	7				ns, Min
T <sub>DNADH</sub>	Hold time on DIN after the rising edge of CLK	1				ns, Min
T <sub>DNARSU</sub>	Setup time on READ before the rising edge of CLK	7				ns, Min
		1,000				ns, Max
T <sub>DNARH</sub>	Hold time on READ after the rising edge of CLK	1				ns, Min
T <sub>DNADCKO</sub>	Clock-to-output delay on DOUT after rising edge of CLK	0.5				ns, Min
		6				ns, Max
T <sub>DNACLKF</sub> <sup>(2)</sup>	CLK frequency	2				MHz, Max
T <sub>DNACLKL</sub>	CLK Low time	50				ns, Min
T <sub>DNACLKH</sub>	CLK High time	50				ns, Min

**Notes:**

1. The minimum READ pulse width is 8 ns, the maximum READ pulse width is 1 μs.
2. Also applies to TCK when reading DNA through the boundary-scan port.

Table 46: Suspend Mode Switching Characteristics

Symbol	Description	Min	Max	Units
<b>Entering Suspend Mode</b>				
T <sub>SUSPENDHIGH_AWAKE</sub>	Rising edge of SUSPEND pin to falling edge of AWAKE pin without glitch filter	2.5	14	ns
T <sub>SUSPENDFILTER</sub>	Adjustment to SUSPEND pin rising edge parameters when glitch filter enabled	31	430	ns
T <sub>SUSPEND_GWE</sub>	Rising edge of SUSPEND pin until FPGA output pins drive their defined SUSPEND constraint behavior (without glitch filter)	–	15	ns
T <sub>SUSPEND_GTS</sub>	Rising edge of SUSPEND pin to write-protect lock on all writable clocked elements (without glitch filter)	–	15	ns
T <sub>SUSPEND_DISABLE</sub>	Rising edge of the SUSPEND pin to FPGA input pins and interconnect disabled (without glitch filter)	–	1500	ns
<b>Exiting Suspend Mode</b>				
T <sub>SUSPENDLOW_AWAKE</sub>	Falling edge of the SUSPEND pin to rising edge of the AWAKE pin. Does not include DCM or PLL lock time.	7	75	μs
T <sub>SUSPEND_ENABLE</sub>	Falling edge of the SUSPEND pin to FPGA input pins and interconnect re-enabled	7	41	μs
T <sub>AWAKE_GWE1</sub>	Rising edge of the AWAKE pin until write-protect lock released on all writable clocked elements, using <b>sw_clk:InternalClock</b> and <b>sw_gwe_cycle:1</b> .	–	80	ns
T <sub>AWAKE_GWE512</sub>	Rising edge of the AWAKE pin until write-protect lock released on all writable clocked elements, using <b>sw_clk:InternalClock</b> and <b>sw_gwe_cycle:512</b> .	–	20.5	μs
T <sub>AWAKE_GTS1</sub>	Rising edge of the AWAKE pin until outputs return to the behavior described in the FPGA application, using <b>sw_clk:InternalClock</b> and <b>sw_gts_cycle:1</b> .	–	80	ns
T <sub>AWAKE_GTS512</sub>	Rising edge of the AWAKE pin until outputs return to the behavior described in the FPGA application, using <b>sw_clk:InternalClock</b> and <b>sw_gts_cycle:512</b> .	–	20.5	μs
T <sub>SCP_AWAKE</sub>	Rising edge of SCP pins to rising edge of AWAKE pin	7	75	μs

## Clock Buffers and Networks

Table 48: Global Clock Switching Characteristics (BUFGMUX)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
T <sub>GSI</sub>	S pin Setup to I0/I1 inputs	LX devices	0.25	0.31	0.48	0.48	ns
		LXT devices	0.25	0.31	0.48	N/A	ns
T <sub>GIO</sub>	BUFGMUX delay from I0/I1 to O	LX devices	0.21	0.21	0.21	0.21	ns
		LXT devices	0.21	0.21	0.21	N/A	ns
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	Global clock tree (BUFGMUX)	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz

Table 49: Input/Output Clock Switching Characteristics (BUFIO2)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
T <sub>BUFCO_O</sub>	Clock to out delay from I to O	LX devices	0.67	0.82	1.09	1.50	ns
		LXT devices	0.67	0.82	1.09	N/A	ns
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	I/O clock tree (BUFIO2)	LX devices	540	525	500	300	MHz
		LXT devices	540	525	500	N/A	MHz

Table 50: Input/Output Clock Switching Characteristics (BUFIO2FB)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	I/O clock tree (BUFIO2FB)	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz

Table 51: Input/Output Clock Switching Characteristics (BUFPLL)

Symbol	Description	Devices	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Maximum Frequency</b>							
F <sub>MAX</sub>	BUFPLL clock tree (BUFPLL)	LX devices	1080	1050	950	500	MHz
		LXT devices	1080	1050	950	N/A	MHz

## PLL Switching Characteristics

Table 52: PLL Specification

Symbol	Description	Device <sup>(1)</sup>	Speed Grade				Units
			-3	-3N	-2	-1L	
F <sub>INMAX</sub>	Maximum Input Clock Frequency from I/O Clock	LX devices	540	525	450	300	MHz
		LXT devices	540	525	450	N/A	MHz
	Maximum Input Clock Frequency from Global Clock	LX devices	400	400	375	250	MHz
		LXT devices	400	400	375	N/A	MHz

## DCM Switching Characteristics

Table 53: Operating Frequency Ranges and Conditions for the Delay-Locked Loop (DLL)<sup>(1)</sup>

Symbol	Description	Speed Grade								Units
		-3		-3N		-2		-1L		
		Min	Max	Min	Max	Min	Max	Min	Max	
<b>Input Frequency Ranges</b>										
CLKIN_FREQ_DLL	Frequency of the CLKIN clock input when the CLKDV output is not used.	5 <sup>(2)</sup>	280 <sup>(3)</sup>	5 <sup>(2)</sup>	280 <sup>(3)</sup>	5 <sup>(2)</sup>	250 <sup>(3)</sup>	5 <sup>(2)</sup>	175 <sup>(3)</sup>	MHz
	Frequency of the CLKIN clock input when using the CLKDV output.	5 <sup>(2)</sup>	280 <sup>(3)</sup>	5 <sup>(2)</sup>	280 <sup>(3)</sup>	5 <sup>(2)</sup>	250 <sup>(3)</sup>	5 <sup>(2)</sup>	133 <sup>(3)</sup>	MHz
<b>Input Pulse Requirements</b>										
CLKIN_PULSE	CLKIN pulse width as a percentage of the CLKIN period for CLKIN_FREQ_DLL < 150 MHz	40	60	40	60	40	60	40	60	%
	CLKIN pulse width as a percentage of the CLKIN period for CLKIN_FREQ_DLL > 150 MHz	45	55	45	55	45	55	45	55	%
<b>Input Clock Jitter Tolerance and Delay Path Variation<sup>(4)</sup></b>										
CLKIN_CYC_JITT_DLL_LF	Cycle-to-cycle jitter at the CLKIN input for CLKIN_FREQ_DLL < 150 MHz	–	±300	–	±300	–	±300	–	±300	ps
CLKIN_CYC_JITT_DLL_HF	Cycle-to-cycle jitter at the CLKIN input for CLKIN_FREQ_DLL > 150 MHz.	–	±150	–	±150	–	±150	–	±150	ps
CLKIN_PER_JITT_DLL	Period jitter at the CLKIN input.	–	±1	–	±1	–	±1	–	±1	ns
CLKFB_DELAY_VAR_EXT	Allowable variation of the off-chip feedback delay from the DCM output to the CLKFB input.	–	±1	–	±1	–	±1	–	±1	ns

**Notes:**

1. DLL specifications apply when using any of the DLL outputs: CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, or CLKDV.
2. When operating independently of the DLL, the DFS supports lower CLKIN\_FREQ\_DLL frequencies. See Table 55.
3. The CLKIN\_DIVIDE\_BY\_2 attribute increases the effective input frequency range. When set to TRUE, the input clock frequency is divided by two as it enters the DCM. Input clock frequencies for the clock buffer being used can be increased up to the F<sub>MAX</sub> (see Table 48 and Table 49 for BUFG and BUFIO2 limits). When used with CLK\_FEEDBACK=2X, the input clock frequency matches the frequency for CLK2X, and is limited to CLKOUT\_FREQ\_2X.
4. CLKIN\_FREQ\_DLL input jitter beyond these limits can cause the DCM to lose LOCK, indicated by the LOCKED output deasserting. The user must then reset the DCM.
5. When using both DCMs in a CMT, both DCMs must be LOCKED.

Table 54: Switching Characteristics for the Delay-Locked Loop (DLL)<sup>(1)</sup> (Cont'd)

Symbol	Description	Speed Grade								Units
		-3		-3N		-2		-1L		
		Min	Max	Min	Max	Min	Max	Min	Max	
LOCK_DLL <sup>(3)</sup>	When using the DLL alone: The time from deassertion at the DCM's reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase. CLKIN_FREQ_DLL < 50 MHz.	-	5	-	5	-	5	-	5	ms
	When using the DLL alone: The time from deassertion at the DCM's reset input to the rising transition at its LOCKED output. When the DCM is locked, the CLKIN and CLKFB signals are in phase. CLKIN_FREQ_DLL > 50 MHz	-	0.60	-	0.60	-	0.60	-	0.60	ms
<b>Delay Lines</b>										
DCM_DELAY_STEP <sup>(5)</sup>	Finest delay resolution, averaged over all steps.	10	40	10	40	10	40	10	40	ps

**Notes:**

1. The values in this table are based on the operating conditions described in Table 2 and Table 53.
2. Indicates the maximum amount of output jitter that the DCM adds to the jitter on the CLKIN input.
3. For optimal jitter tolerance and faster LOCK time, use the CLKIN\_PERIOD attribute.
4. Some jitter and duty-cycle specifications include 1% of input clock period or 0.01 UI. For example, this data sheet specifies a maximum jitter of ±(1% of CLKIN period + 150 ps). Assuming that the CLKIN frequency is 100 MHz, the equivalent CLKIN period is 10 ns. Since 1% of 10 ns is 0.1 ns or 100 ps, the maximum jitter is ±(100 ps + 150 ps) = ±250 ps.
5. A typical delay step size is 23 ps.
6. The timing analysis tools use the CLK\_FEEDBACK = 1X condition for the CLKIN\_CLKFB\_PHASE value (reported as phase error). When using CLK\_FEEDBACK = 2X, add 100 ps to the phase error for the CLKIN\_CLKFB\_PHASE value (as shown in this table).

Table 55: Recommended Operating Conditions for the Digital Frequency Synthesizer (DFS)<sup>(1)</sup>

Symbol	Description	Speed Grade								Units
		-3		-3N		-2		-1L		
		Min	Max	Min	Max	Min	Max	Min	Max	
<b>Input Frequency Ranges<sup>(2)</sup></b>										
CLKIN_FREQ_FX	Frequency for the CLKIN input. Also described as F <sub>CLKIN</sub> .	0.5	375 <sup>(3)</sup>	0.5	375 <sup>(3)</sup>	0.5	333 <sup>(3)</sup>	0.5	200 <sup>(3)</sup>	MHz
<b>Input Clock Jitter Tolerance<sup>(4)</sup></b>										
CLKIN_CYC_JITT_FX_LF	Cycle-to-cycle jitter at the CLKIN input, based on CLKFX output frequency: F <sub>CLKFX</sub> < 150 MHz.	-	±300	-	±300	-	±300	-	±300	ps
CLKIN_CYC_JITT_FX_HF	Cycle-to-cycle jitter at the CLKIN input, based on CLKFX output frequency: F <sub>CLKFX</sub> > 150 MHz.	-	±150	-	±150	-	±150	-	±150	ps
CLKIN_PER_JITT_FX	Period jitter at the CLKIN input.	-	±1	-	±1	-	±1	-	±1	ns

**Notes:**

1. DFS specifications apply when using either of the DFS outputs (CLKFX or CLKFX180).
2. When using both DFS and DLL outputs on the same DCM, follow the more restrictive CLKIN\_FREQ\_DLL specifications in Table 53.
3. The CLKIN\_DIVIDE\_BY\_2 attribute increases the effective input frequency range. When set to TRUE, the input clock frequency is divided by two as it enters the DCM. Input clock frequencies for the clock buffer being used can be increased up to the F<sub>MAX</sub> (see Table 48 and Table 49 for BUFG and BUFI02 limits).
4. CLKIN input jitter beyond these limits can cause the DCM to lose LOCK.



**Table 65: Global Clock Input to Output Delay With DCM in Source-Synchronous Mode**

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
LVCMOS25 Global Clock Input to Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, <i>with</i> DCM in Source-Synchronous Mode.							
T <sub>ICKOFDCM_0</sub>	Global Clock and OUTFF <i>with</i> DCM	XC6SLX4	5.03	N/A	7.21	8.05	ns
		XC6SLX9	5.03	6.13	7.21	8.05	ns
		XC6SLX16	5.08	5.51	6.44	7.96	ns
		XC6SLX25	4.81	5.13	5.69	7.94	ns
		XC6SLX25T	4.81	5.13	5.69	N/A	ns
		XC6SLX45	5.26	5.69	6.63	7.92	ns
		XC6SLX45T	5.26	5.69	6.63	N/A	ns
		XC6SLX75	4.77	5.18	5.88	7.95	ns
		XC6SLX75T	4.77	5.18	5.88	N/A	ns
		XC6SLX100	4.72	5.11	5.76	8.59	ns
		XC6SLX100T	4.76	5.11	5.76	N/A	ns
		XC6SLX150	4.90	5.30	5.93	7.93	ns
		XC6SLX150T	4.90	5.30	5.93	N/A	ns
		XA6SLX4	5.35	N/A	7.21	N/A	ns
		XA6SLX9	5.35	N/A	7.21	N/A	ns
		XA6SLX16	5.42	N/A	6.44	N/A	ns
		XA6SLX25	5.13	N/A	5.69	N/A	ns
		XA6SLX25T	5.13	N/A	5.79	N/A	ns
		XA6SLX45	5.58	N/A	6.63	N/A	ns
		XA6SLX45T	5.58	N/A	6.63	N/A	ns
		XA6SLX75	5.09	N/A	5.87	N/A	ns
		XA6SLX75T	5.09	N/A	5.87	N/A	ns
		XA6SLX100	N/A	N/A	6.44	N/A	ns
		XQ6SLX75	N/A	N/A	5.87	7.95	ns
XQ6SLX75T	5.09	N/A	5.87	N/A	ns		
XQ6SLX150	N/A	N/A	6.06	7.93	ns		
XQ6SLX150T	5.50	N/A	6.06	N/A	ns		

**Notes:**

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. DCM output jitter is already included in the timing calculation.

Table 66: Global Clock Input to Output Delay With PLL in System-Synchronous Mode

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
LVCMOS25 Global Clock Input to Output Delay using Output Flip-Flop, 12mA, Fast Slew Rate, with PLL in System-Synchronous Mode.							
T <sub>ICKOFFPLL</sub>	Global Clock and OUTFF with PLL	XC6SLX4	4.57	N/A	6.25	7.34	ns
		XC6SLX9	4.57	5.25	6.25	7.34	ns
		XC6SLX16	4.41	4.64	5.39	6.92	ns
		XC6SLX25	4.03	4.32	4.91	7.64	ns
		XC6SLX25T	4.03	4.32	4.91	N/A	ns
		XC6SLX45	4.63	4.96	5.75	7.36	ns
		XC6SLX45T	4.63	4.96	5.75	N/A	ns
		XC6SLX75	4.01	4.30	4.88	7.15	ns
		XC6SLX75T	4.01	4.30	4.88	N/A	ns
		XC6SLX100	4.02	4.33	4.90	7.37	ns
		XC6SLX100T	4.06	4.33	4.90	N/A	ns
		XC6SLX150	3.65	3.98	4.58	6.94	ns
		XC6SLX150T	3.65	3.98	4.58	N/A	ns
		XA6SLX4	4.88	N/A	6.13	N/A	ns
		XA6SLX9	4.88	N/A	6.13	N/A	ns
		XA6SLX16	4.74	N/A	5.27	N/A	ns
		XA6SLX25	4.43	N/A	4.78	N/A	ns
		XA6SLX25T	4.43	N/A	4.88	N/A	ns
		XA6SLX45	4.94	N/A	5.62	N/A	ns
		XA6SLX45T	4.94	N/A	5.62	N/A	ns
		XA6SLX75	4.32	N/A	4.77	N/A	ns
		XA6SLX75T	4.32	N/A	4.77	N/A	ns
		XA6SLX100	N/A	N/A	5.41	N/A	ns
		XQ6SLX75	N/A	N/A	4.77	7.15	ns
XQ6SLX75T	4.32	N/A	4.77	N/A	ns		
XQ6SLX150	N/A	N/A	4.60	6.94	ns		
XQ6SLX150T	4.35	N/A	4.60	N/A	ns		

Notes:

1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. PLL output jitter is included in the timing calculation.

## Spartan-6 Device Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. The representative values for typical pin locations and normal clock loading are listed in Table 70 through Table 77. Values are expressed in nanoseconds unless otherwise noted.

Table 70: Global Clock Setup and Hold Without DCM or PLL (No Delay)

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Input Setup and Hold Time Relative to Global Clock Input Signal for LVC MOS25 Standard.<sup>(1)</sup></b>							
T <sub>PSND</sub> / T <sub>PHND</sub>	No Delay Global Clock and IFF <sup>(3)</sup> without DCM or PLL	XC6SLX4	0.10/1.56	N/A	0.10/1.83	0.07/2.54	ns
		XC6SLX9	0.10/1.56	0.10/1.57	0.10/1.84	0.07/2.54	ns
		XC6SLX16	0.12/1.42	0.12/1.48	0.12/1.64	0.13/2.19	ns
		XC6SLX25	0.18/1.64	0.18/1.75	0.18/1.99	0.11/2.57	ns
		XC6SLX25T	0.18/1.64	0.18/1.75	0.18/1.99	N/A	ns
		XC6SLX45	-0.08/1.80	-0.08/1.95	-0.08/2.27	-0.17/2.74	ns
		XC6SLX45T	-0.08/1.80	-0.08/1.95	-0.08/2.27	N/A	ns
		XC6SLX75	0.13/1.81	0.13/2.06	0.13/2.27	-0.12/3.30	ns
		XC6SLX75T	0.13/1.81	0.13/2.06	0.13/2.27	N/A	ns
		XC6SLX100	-0.14/2.03	-0.14/2.24	-0.14/2.56	-0.17/3.44	ns
		XC6SLX100T	-0.14/2.03	-0.14/2.24	-0.14/2.56	N/A	ns
		XC6SLX150	-0.24/2.42	-0.24/2.74	-0.24/2.95	-0.60/3.75	ns
		XC6SLX150T	-0.24/2.42	-0.24/2.74	-0.24/2.95	N/A	ns
		XA6SLX4	0.10/1.57	N/A	0.10/1.84	N/A	ns
		XA6SLX9	0.10/1.57	N/A	0.10/1.84	N/A	ns
		XA6SLX16	0.12/1.43	N/A	0.12/1.64	N/A	ns
		XA6SLX25	0.18/1.65	N/A	0.18/1.99	N/A	ns
		XA6SLX25T	0.18/1.65	N/A	0.18/1.99	N/A	ns
		XA6SLX45	-0.08/1.82	N/A	-0.08/2.27	N/A	ns
		XA6SLX45T	-0.08/1.82	N/A	-0.08/2.27	N/A	ns
		XA6SLX75	0.13/2.02	N/A	0.13/2.32	N/A	ns
		XA6SLX75T	0.13/2.02	N/A	0.13/2.32	N/A	ns
		XA6SLX100	N/A	N/A	0.10/2.51	N/A	ns
		XQ6SLX75	N/A	N/A	0.13/2.32	-0.12/3.30	ns
XQ6SLX75T	0.13/2.02	N/A	0.13/2.32	N/A	ns		
XQ6SLX150	N/A	N/A	-0.24/2.95	-0.60/3.75	ns		
XQ6SLX150T	-0.24/2.74	N/A	-0.24/2.95	N/A	ns		

**Notes:**

1. Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage.
2. IFF = Input Flip-Flop or Latch.

Table 71: Global Clock Setup and Hold Without DCM or PLL (Default Delay)

Symbol	Description	Device	Speed Grade				Units
			-3	-3N	-2	-1L	
<b>Input Setup and Hold Time Relative to Global Clock Input Signal for LVC MOS25 Standard.<sup>(1)</sup></b>							
T <sub>PSFD</sub> / T <sub>PHFD</sub>	Default Delay <sup>(2)</sup> Global Clock and IFF <sup>(3)</sup> without DCM or PLL	XC6SLX4	0.66/1.17	N/A	1.05/0.79	2.09/1.05	ns
		XC6SLX9	0.66/1.17	0.75/1.17	1.05/1.17	2.09/1.05	ns
		XC6SLX16	0.87/1.16	0.93/1.16	0.96/1.16	1.86/1.06	ns
		XC6SLX25	0.68/0.77	0.81/0.81	0.87/0.82	2.21/1.33	ns
		XC6SLX25T	0.68/0.77	0.81/0.81	0.87/0.82	N/A	ns
		XC6SLX45	0.40/1.05	0.42/1.17	0.64/1.20	1.61/1.67	ns
		XC6SLX45T	0.40/1.05	0.42/1.17	0.64/1.20	N/A	ns
		XC6SLX75	0.41/1.11	0.41/1.13	0.80/1.14	1.23/1.82	ns
		XC6SLX75T	0.41/1.11	0.41/1.13	0.80/1.14	N/A	ns
		XC6SLX100	0.39/1.12	0.39/1.23	0.39/1.28	1.13/1.94	ns
		XC6SLX100T	0.39/1.12	0.39/1.23	0.39/1.28	N/A	ns
		XC6SLX150	0.23/1.54	0.23/1.62	0.23/1.62	1.14/2.05	ns
		XC6SLX150T	0.23/1.54	0.23/1.62	0.23/1.62	N/A	ns
		XA6SLX4	0.73/1.18	N/A	1.05/0.80	N/A	ns
		XA6SLX9	0.73/1.18	N/A	1.05/0.80	N/A	ns
		XA6SLX16	0.90/1.20	N/A	0.96/0.75	N/A	ns
		XA6SLX25	0.70/0.81	N/A	0.87/0.91	N/A	ns
		XA6SLX25T	0.76/0.81	N/A	1.03/0.91	N/A	ns
		XA6SLX45	0.40/1.06	N/A	0.64/1.20	N/A	ns
		XA6SLX45T	0.40/1.06	N/A	0.64/1.20	N/A	ns
		XA6SLX75	0.41/1.24	N/A	0.80/1.18	N/A	ns
		XA6SLX75T	0.41/1.24	N/A	0.80/1.18	N/A	ns
		XA6SLX100	N/A	N/A	0.86/1.55	N/A	ns
		XQ6SLX75	N/A	N/A	0.80/1.18	1.23/1.82	ns
		XQ6SLX75T	0.41/1.24	N/A	0.80/1.18	N/A	ns
		XQ6SLX150	N/A	N/A	0.28/1.57	1.14/2.05	ns
XQ6SLX150T	0.28/1.78	N/A	0.28/1.57	N/A	ns		

**Notes:**

1. Setup and Hold times are measured over worst case conditions (process, voltage, temperature). Setup time is measured relative to the Global Clock input signal using the slowest process, highest temperature, and lowest voltage. Hold time is measured relative to the Global Clock input signal using the fastest process, lowest temperature, and highest voltage.
2. Default delay uses IODELAY2 tap 0.
3. IFF = Input Flip-Flop or Latch.

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